GSE033LB1D5F

ESD Protection Diode

Product Description

It is designed to protect sensitive electronics from damage due to electrostatic discharge (ESD) and other transient events.

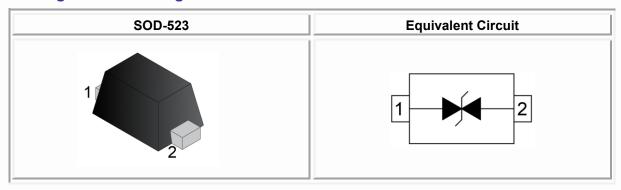
Features

- Operating Voltage: 3.3V.
- IEC61000-4-2(ESD) ±30kV (Air)
- IEC61000-4-2(ESD) ±30kV (Contact)
- IEC61000-4-5(Lighting) 8A (8/20µs)

Mechanical Data

- SOD-523 Package
- RoHS Compliant and Halogen Free

Package and Pin Assignment





Ordering and Marking Information

GS P/N	Package	Marking	Quantity / Reel
GSE033LB1D3F	SOD-523 3Y 3,000		3,000PCS
GSE033LB1D3F - Product Code: GSE033LB1 - Package Code: - Green Level: F for RoHS Com Halogen Free			RoHS Compliant and
	Marking	Information	
3Y	- Product Code 3Y	9:	

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit
P _{PP}	Peak Pulse Power (t _P =8/20µs)	80	W
IPP	Peak Pulse Current (t⊳=8/20µs)	8	А
	ESD Per IEC61000-4-2 (Air)	±30	KV
VESD	ESD Per IEC61000-4-2 (Contact)	±30	KV
TJ	Operating Junction Temperature Range	-55 to +125	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

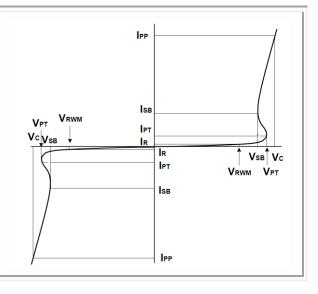


Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{RWM}	Reverse Working Voltage	-			3.3	V
V _{PT}	Punch-Through Voltage	I _{PT} = 2µA	3.8			V
V _{SB}	Snap-Back Voltage	I _{SB} = 50mA	3.5			V
I _R	Reverse Leakage Current	V _{RWM} =3.3V			0.2	μA
		I _{PP} =1A (8/20µs)			6.0	V
Vc	Clamping Voltage	I _{PP} =5A (8/20μs)			8.0	V
		I _{PP} =8A (8/20µs)			10	V
Сл	Junction Capacitance	V _R =0V, f=1MHz		12.5	20	pF

Electrical Parameters

Symbol	Parameter	
Ірр	Maximum Reverse Peak Pulse Current	
Vc	Clamping Voltage @ IPP	
V _{RWM}	Working Peak Reverse Voltage	
I _R	Maximum Reverse Leakage Current @ V _{RWM}	
V _{PT}	Punch-through Breakdown Voltage @ I _{PT}	
VsB	Snap-Back Voltage @ IsB	
I _{SB}	Snap-Back Current	
I _{PT}	Test Current	





Typical Characteristics (T_A=25°C unless otherwise specified)

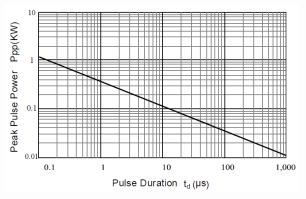


Fig 1. Peak Pulse Power vs. Pulse Time

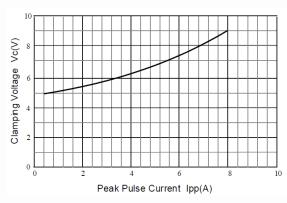


Fig 3. Clamping Voltage vs. Peak Pulse Current

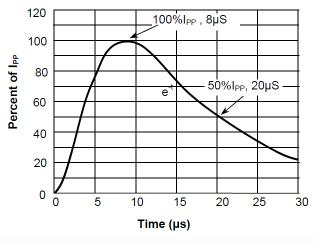


Fig 5. 8 X 20µs Pulse Waveform

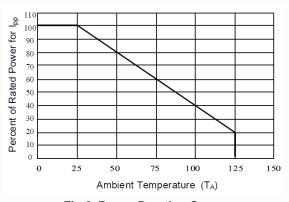


Fig 2. Power Derating Curve

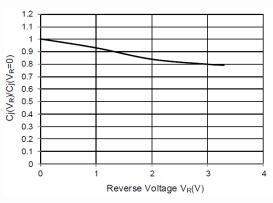


Fig 4. Junction Capacitance vs. Reverse Voltage

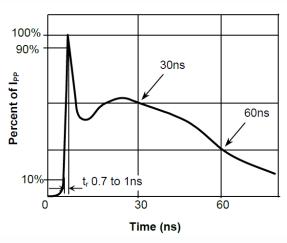
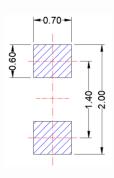


Fig 6. ESD(IEC61000-4-2) Pulse Waveform

SOD-523

Package Dimension

Recommended Land Pattern



Unit:mm

	Dimensions				
0	Millimeters		Inches		
Symbol	MIN	MAX	MIN	MAX	
Α	0.50	0.77	0.020	0.030	
b	0.25	0.40	0.010	0.016	
С	0.07	0.20	0.003	0.008	
D	0.70	0.90	0.028	0.035	
E	1.50	1.70	0.059	0.067	
E1	1.10	1.30	0.043	0.051	
L	0.20 REF.		0.008 I	REF	

NOTE:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



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